Customer Information Notification	2016080011

Issue Date: 21-Sep-2016
Effective Date: 22-Sep-2016

Management Summary

The i.MX 6 errata documentation has been updated for i.MX6 Solo and DualLite Family of Devices.

Change Category

☐ Wafer Fab Process	☐ Assembly Process	☐ Product Marking	☐ Test Location	☐ Design
☐ Wafer Fab Materials	☐ Assembly Materials	☐ Mechanical Specification	☐ Test Process	☑ Errata
☐ Wafer Fab Location	☐ Assembly Location	☐ Packing/Shipping/Labeling	☐ Test Equipment	☐ Electrical spec./Test coverage

i.MX6 Solo/DualLite Chip Errata Revision

Information Notification

The updated errata documentation is attached to this notice and can be found at:
http://www.nxp.com/files/32bit/doc/errata/IMX6SDLCE.pdf?fasp=1&WT_TYPE=Errata&WT_VENDOR=FREESCALE&WT_FILE_FORMAT=pdf&WT_ASSET=Documentation&fileExt=.pdf

There is a full list of updates for both ARM and i.MX 6Solo/DualLite in the attached errata document.

The errata describes existing conditions identified on current production devices. There are potential hardware and/or software implications to customers.

Why do we issue this Information Notification

NXP informs all customers of new documentation available on www.nxp.com for i.MX6 Family of Devices.

Identification of Affected Products

Product identification does not change

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Additional information

Additional documents: [view online](#)

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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